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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/533,291	02/07/2006	Paul Colfer	200316610-2	6028

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EXAMINER

HO, ANTHONY

ART UNIT	PAPER NUMBER
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2815

MAIL DATE	DELIVERY MODE
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09/27/2007

PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No. 10/533,291	Applicant(s) COLFER ET AL.	
	Examiner Anthony Ho	Art Unit 2815	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 21 August 2007.
 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-20,22-30,63,64,68,71,74 and 75 is/are pending in the application.
 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
 5) ☐ Claim(s) _____ is/are allowed.
 6) ☒ Claim(s) 1-20,22-30,63,64,68,71,74 and 75 is/are rejected.
 7) ☐ Claim(s) _____ is/are objected to.
 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
 10) ☒ The drawing(s) filed on 14 September 2007 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 a) ☐ All b) ☐ Some * c) ☐ None of:
 1. ☐ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08)
Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

This is in response to amendment to application no. 10/533,291 filed on August 21, 2007.

Claims 1-20, 22-30, 63-64, 68, 71 and 74-75 are presented for examination. Claims 76-88 have been cancelled.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 1-20, 22-30, 63-64, 68, 71, and 74-75 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yudasaka et al (EP 1085578) in view of Grigoropoulos et al (US PUB 2004/0137710).

In re claims 1-3, Yudasaka et al discloses a method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing inorganic semi-conducting nanoparticles and dopant on a substrate, the nanoparticles comprising a group four element such as silicon or germanium; fusing the nanoparticles by heating to form a continuous layer; and subsequently; recrystallizing the layer (paragraph 0004; paragraph 0045 – paragraph 0066).

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Grigoropoulos et al discloses the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting (paragraph 0029 – paragraph 0031).

The advantage is the need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect (paragraph 0006).

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified the method of manufacturing an electronic component as taught by Yudasaka et al with the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting as taught by Grigoropoulos et al since there is a need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect.

In re claims 4-6, Yudasaka et al discloses the step of fusing and/or recrystallizing is carried out in a reducing atmosphere (paragraph 0065).

In re claims 7-10, Yudasaka et al discloses the step of heating using laser pulses and cooling (paragraph 0045 – paragraph 000070).

In re claims 11-13, Yudasaka et al discloses the nanoparticles are deposited in a suspension of a carrier fluid (paragraph 0069 – paragraph 0074).

In re claims 14-18, Yudasaka et al discloses the different printing processes (paragraph 0045 – paragraph 0075).

In re claims 19-20, Yudasaka et al discloses the electronic component is a transistor, capacitor, or a diode (Figure 5; Figure 6; Figure 7).

In re claims 22-26, Yudasaka et al discloses a method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing discrete nanoparticles of semi-conducting material with a dopant on a substrate; fusing the nanoparticles with one or more first laser pulses to form a continuous layer; and subsequently; recrystallizing the continuous layer (paragraph 0004; paragraph 0045 – paragraph 0075).

Grigoropoulos et al discloses the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting (paragraph 0029 – paragraph 0031).

The advantage is the need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect (paragraph 0006).

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified the method of manufacturing an electronic component as taught by Yudasaka et al with the nanoparticles are a solid in liquid

suspension and the nanoparticles are formed on a substrate through a physical change of melting as taught by Grigoropoulos et al since there is a need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect.

In re claims 27-29, Yudasaka et al discloses the step of fusing and/or recrystallizing is carried out in a reducing atmosphere (paragraph 0065).

In re claim 30, Yudasaka et al discloses the electronic component is a transistor, capacitor, or a diode (Figure 5; Figure 6; Figure 7).

In re claims 63-64 and 68, Yudasaka et al discloses both a first semiconducting material and a second semiconducting material (paragraph 0045 – paragraph 0070; Example 1).

In re claim 71, Yudasaka et al discloses depositing nanoparticles on a further substrate, causing the nanoparticles to fuse and recrystallise to form a recrystallized film or layer (paragraph 0045 – paragraph 0070; Example 1).

In re claims 74-75, Yudasaka et al discloses a component using the above method (Example 1; Figure 5, Figure 6, Figure 7).

Furthermore, the claimed invention is a product-by-process claim and even though product-by-process claims are limited by and defined by the process, determination of

patentability is based on the product itself. The patentability of a product does not depend on its method of production. If the product in the product-by-process claim is the same as or obvious from a product of the prior art, the claim is unpatentable even though the prior product was made by a different process." *In re Thorpe*, 777 F.2d 695, 698, 227 USPQ 964, 966 (Fed. Cir. 1985).

Claims 1-20, 22-30, 63-64, 68, 71, and 74-75 are rejected under 35 U.S.C. 103(a) as being unpatentable over Furusawa et al (WO 00/59044) in view of Grigoropoulos et al (US PUB 2004/0137710).

In re claims 1-3, Furusawa et al discloses a method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing inorganic semi-conducting nanoparticles and dopant on a substrate, the nanoparticles comprising a group four element such as silicon or germanium; fusing the nanoparticles by heating to form a continuous layer; and subsequently; recrystallizing the layer (column 9 – column 12).

Grigoropoulos et al discloses the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting (paragraph 0029 – paragraph 0031).

The advantage is the need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect (paragraph 0006).

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified the method of manufacturing an electronic component as taught by Furusawa et al with the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting as taught by Grigoropoulos et al since there is a need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect.

In re claims 4-6, Furusawa et al discloses the step of fusing and/or recrystallizing is carried out in a reducing atmosphere (column 9 – column 12).

In re claims 7-10, Furusawa et al discloses the step of heating using laser pulses and cooling (column 9 – column 12).

In re claims 11-13, Furusawa et al discloses the nanoparticles are deposited in a suspension of a carrier fluid (column 9 – column 12).

In re claims 14-18, Furusawa et al discloses the different printing processes (column 9 – column 12).

In re claims 19-20, Furusawa et al discloses the electronic component is a transistor, capacitor, or a diode (Figure 3; Figure 4; Figure 5).

In re claims 22-26, Furusawa et al discloses a method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing discrete nanoparticles of semi-conducting material with a dopant on a substrate; fusing the nanoparticles with one or more first laser pulses to form a continuous layer; and subsequently; recrystallizing the continuous layer (column 9 – column 12).

Grigoropoulos et al discloses the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting (paragraph 0029 – paragraph 0031).

The advantage is the need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect (paragraph 0006).

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified the method of manufacturing an electronic component as taught by Furusawa et al with the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting as taught by Grigoropoulos et al since there is a need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect.

In re claims 27-29, Furusawa et al discloses the step of fusing and/or recrystallizing is carried out in a reducing atmosphere (column 9 – column 12).

In re claim 30, Furusawa et al discloses the electronic component is a transistor, capacitor, or a diode (Figure 3; Figure 4; Figure 5).

In re claims 63-64 and 68, Furusawa et al discloses both a first semiconducting material and a second semiconducting material (column 9 – column 12; Example 1).

In re claim 71, Furusawa et al discloses depositing nanoparticles on a further substrate, causing the nanoparticles to fuse and recrystallise to form a recrystallized film or layer (column 9 – column 12; Example 1).

In re claims 74-75, Furusawa et al discloses a component using the above method (Example 1; Figure 3; Figure 4; Figure 5).

Furthermore, the claimed invention is a product-by-process claim and even though product-by-process claims are limited by and defined by the process, determination of patentability is based on the product itself. The patentability of a product does not depend on its method of production. If the product in the product-by-process claim is the same as or obvious from a product of the prior art, the claim is unpatentable even though the prior product was made by a different process." *In re Thorpe*, 777F.2d 695, 698, 227 USPQ 964, 966 (Fed. Cir. 1985).

Claims 1-20, 22-30, 63-64, 68, 71, and 74-75 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kamata et al (US Patent 6,086,945) in view of Grigoropoulos et al (US PUB 2004/0137710).

In re claims 1-3, Kamata et al discloses a method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing inorganic semi-conducting nanoparticles and dopant on a substrate, the nanoparticles comprising a group four element such as silicon or germanium; fusing the nanoparticles by heating to form a continuous layer; and subsequently; recrystallizing the layer (column 5 – column 11).

Grigoropoulos et al discloses the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting (paragraph 0029 – paragraph 0031).

The advantage is the need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect (paragraph 0006).

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified the method of manufacturing an electronic component as taught by Kamata et al with the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting as taught by Grigoropoulos et al since there is a need for simple and efficient

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devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect.

In re claims 4-6, Kamata et al discloses the step of fusing and/or recrystallizing is carried out in a reducing atmosphere (column 5 – column 11).

In re claims 7-10, Kamata et al discloses the step of heating using laser pulses and cooling (column 5 – column 11).

In re claims 11-13, Kamata et al discloses the nanoparticles are deposited in a suspension of a carrier fluid (column 5 – column 11).

In re claims 14-18, Kamata et al discloses the different printing processes (column 5 – column 11).

In re claims 19-20, Kamata et al discloses the electronic component is a transistor, capacitor, or a diode (Figure 4A; Figure 4B; Figure 13).

In re claims 22-26, Kamata et al discloses a method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing discrete nanoparticles of semi-conducting material with a dopant on a substrate; fusing the nanoparticles with one or more first laser pulses to form a

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continuous layer; and subsequently; recrystallizing the continuous layer (column 5 – column 11).

Grigoropoulos et al discloses the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting (paragraph 0029 – paragraph 0031).

The advantage is the need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect (paragraph 0006).

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified the method of manufacturing an electronic component as taught by Kamata et al with the nanoparticles are a solid in liquid suspension and the nanoparticles are formed on a substrate through a physical change of melting as taught by Grigoropoulos et al since there is a need for simple and efficient devices and method of producing structures from nanoparticles without the need for recesses on the surface in which the particles collect.

In re claims 27-29, Kamata et al discloses the step of fusing and/or recrystallizing is carried out in a reducing atmosphere (column 5 – column 11).

In re claim 30, Kamata et al discloses the electronic component is a transistor, capacitor, or a diode (Figure 4A; Figure 4B; Figure 13).

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In re claims 63-64 and 68, Kamata et al discloses both a first semiconducting material and a second semiconducting material (column 5 – column 11).

In re claim 71, Kamata et al discloses depositing nanoparticles on a further substrate, causing the nanoparticles to fuse and recrystallise to form a recrystallized film or layer (column 5 – column 11).

In re claims 74-75, Kamata et al discloses a component using the above method (column 5 – column 11).

Furthermore, the claimed invention is a product-by-process claim and even though product-by-process claims are limited by and defined by the process, determination of patentability is based on the product itself. The patentability of a product does not depend on its method of production. If the product in the product-by-process claim is the same as or obvious from a product of the prior art, the claim is unpatentable even though the prior product was made by a different process." *In re Thorpe*, 777F.2d 695, 698, 227 USPQ 964, 966 (Fed. Cir. 1985).

Response to Arguments

Applicant's arguments with respect to claims 1 and 22 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

- a. Dutta (US PUB 2003/0047816)
- b. Quick (US Patent 5,391,841)

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

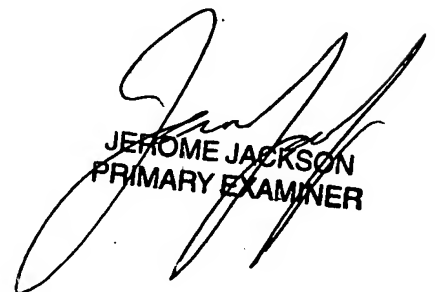
A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than **SIX MONTHS** from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Anthony Ho whose telephone number is 571-270-1432. The examiner can normally be reached on M-Th: 8:30AM-7:00PM EST.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kenneth Parker can be reached on 571-272-2298. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

AH
September 20, 2007


JEROME JACKSON
PRIMARY EXAMINER